



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: **1756**

Serial No.: **10/670,291**

Examiner: **Daborah Chako-Davis**

Filed: **September 26, 2003**

Confirmation No.: **6427**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR
FORMING RESIST PATTERN, AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: **031181**

Customer Number: **38834**

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Date: February 7, 2005

Sir:

In response to the Office Action dated October 5, 2004, **the response date of which having been extended by one month to February 5, 2005**, Applicants amend the claims as follows and submit the following remarks.

Amendments to the Claims are reflected in the listing of claims that begins on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.